



**NOTES**

1. PLATING THICKNESS TO BE PER CUSTOMER'S SPECIFICATION.
2. SEAL AREA TO BE METALLIZED.
3. DIE ATTACH AREA TO BE METALLIZED.
4. SEAL RING TO BE FLOATING FROM ANY LEADS.
5. LEAD RESISTANCE : 0.10 OHM MAX. AT LEAD NO.9,18 OTHER LESS THAN 0.20 OHM MAX.
6. WIRE BOND PAD CONNECTED TO CORRESPONDED OUTER LEADS.
7. MISALIGNMENT OF METALLIZATION PATTERN IN CAVITY SHALL BE ACCEPTED DUE TO LAYER MISALIGNMENT.



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